

Zener Protection Diode

NZ8DH Series

The NZ8DH devices are designed for applications requiring transient overvoltage ESD protection. They are intended to protect voltage sensitive components from ESD and other harmful transient voltage events. This device provides a single channel of bidirectional protection in an, ultra-compact XDFNW2 1.0 x 0.6 mm package. This device is ideal to replace SOT23 or other dual diode 3 pin devices used as single line bi-directional protection.

Features

- Precise Clamping Voltage
- High ESD Ratings
- Wettable Flank Package for optimal Automated Optical Inspection (AOI)
- 175°C T_{J(MAX)} – Rated for High Temperature, Mission Critical Applications
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Automotive ECU's
- In Vehicle Networking (IVN)
- Voltage Sensitive Circuits

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
IEC 61000-4-2 Contact (Note 1)	ESD	±30	kV
IEC 61000-4-2 Air		±30	kV
ISO 10605 Contact (330 pF / 330 Ω) ≤ 9.1 V > 9.1 V		±30 ±26	kV
ISO 10605 Contact (330 pF / 2 kΩ)		±30	kV
ISO 10605 Contact (150 pF / 2 kΩ)		±30	kV
Maximum Peak Pulse Current (8/20 μs) (Note 2)	I _{pp}	4.5	A
Total Power Dissipation (Note 3 @ T _A = 25°C Thermal Resistance, Junction-to-Ambient	P _D R _{θJA}	300 400	mW °C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +175	°C

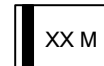
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Non-repetitive current pulse at T_A = 25°C, per IEC61000-4-2 waveform.
2. Non-repetitive current pulse per figure 1.
3. Mounted with recommended minimum pad size, DC board FR-4



XDFNW2
CASE 521AE

DEVICE MARKING INFORMATION



XX = Specific Device Code
M = Date Code

ORDERING INFORMATION

Device	Package	Shipping†
NZ8DHxxxMXWT5G	XDFNW2 (Pb-Free)	8000 / Tape & Reel
SZ8DHxxxMXWT5G		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NZ8DH Series

ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

Symbol	Parameter
I _{PP}	Maximum Reverse Peak Pulse Current (8/20 μs)
V _C	Clamping Voltage @ I _{PP}
V _{RWM}	Working Peak Reverse Voltage
I _R	Maximum Reverse Leakage Current @ V _{RWM}
V _{BR}	Breakdown Voltage @ I _T
I _T	Test Current

*See Application Note AND8308/D for detailed explanations of datasheet parameters.

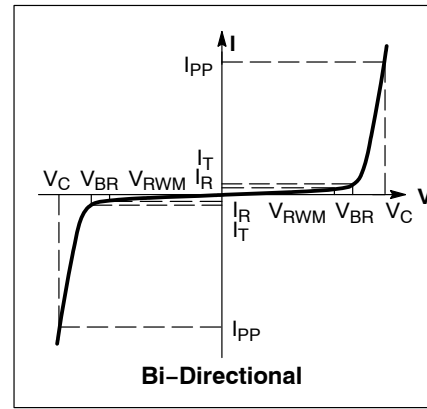


Figure 1.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Device*	Device Marking	V _{RWM} Max	V _{BR} I _T = 5 mA (Note 4)		I _R (μA) Max @ V _{RWM}	V _C Typ @ I _{PP} = 1.0 A	C(pF) Typ @ V _R = 0 V, f = 1 MHz
			Min	Max			
NZ8DH2V4†		1	3.00	3.60	50	3.70	60
NZ8DH2V7†		1	3.28	3.92	20	4.00	55
NZ8DH3V0†		1	3.55	4.25	10	4.30	54
NZ8DH3V3†		1	3.82	4.58	10	4.60	50
NZ8DH3V6†		1	4.10	4.91	10	4.90	48
NZ8DH3V9†		1	4.37	5.23	5	5.20	45
NZ8DH4V3†		1	4.73	5.67	5	5.60	42
NZ8DH4V7†		1	5.10	6.10	2	6.10	40
NZ8DH5V1†		1.5	5.46	6.54	2	6.50	38
NZ8DH5V6†		2.5	5.92	7.09	1	7.10	36
NZ8DH6V2†		3	6.46	7.74	1	7.70	35
NZ8DH6V8†		3.5	7.01	8.39	0.5	8.40	32
NZ8DH7V5†		4	7.64	9.16	0.5	9.20	30
NZ8DH8V2†		5	8.28	9.92	0.5	9.90	28
NZ8DH9V1MXWT5G	AA	6	9.30	10.70	0.5	10.90	25
NZ8DH10V†		7	10.14	11.66	0.1	11.90	23
NZ8DH11V†		8	11.07	12.73	0.1	13.00	22
NZ8DH12V†		9	12.00	13.80	0.1	14.10	20
NZ8DH13V†		10	12.93	14.87	0.1	15.20	19
NZ8DH15V†		11	14.79	17.01	0.1	17.40	18
NZ8DH16V†		12	15.72	18.08	0.1	18.50	18
NZ8DH18V†		14	17.58	20.22	0.1	20.70	17
NZ8DH20V†		15.4	19.44	22.36	0.1	22.90	16
NZ8DH22V†		16.8	21.30	24.50	0.1	25.10	14
NZ8DH24V†		18.9	23.16	26.64	0.1	27.30	12
NZ8DH27VMXWT5G	A5	22	25.95	29.85	0.1	30.70	12
NZ8DH33VMXWT5G	A6	26	31.53	36.27	0.1	37.30	10
NZ8DH47VMXWT5G	A7	38	44.55	51.25	0.1	52.70	8

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

*Includes SZ prefix where applicable: SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

†Consult factory on availability.

4. Breakdown voltage is tested from pin 1 to 2 and pin 2 to 1.

NZ8DH Series

TYPICAL CHARACTERISTICS

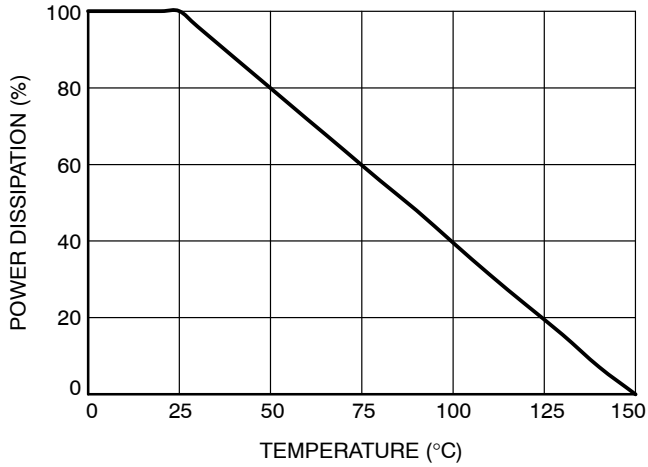


Figure 2. Steady State Power Derating

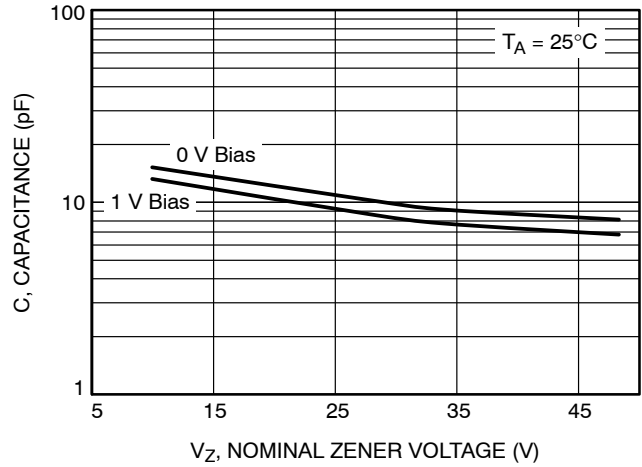


Figure 3. Typical Capacitance

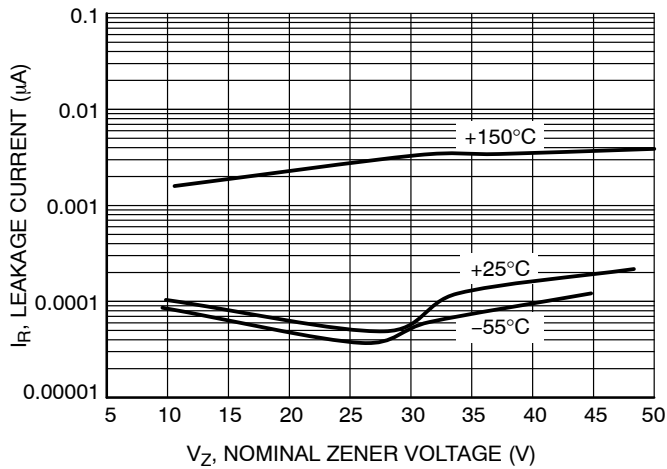


Figure 4. Typical Leakage Current

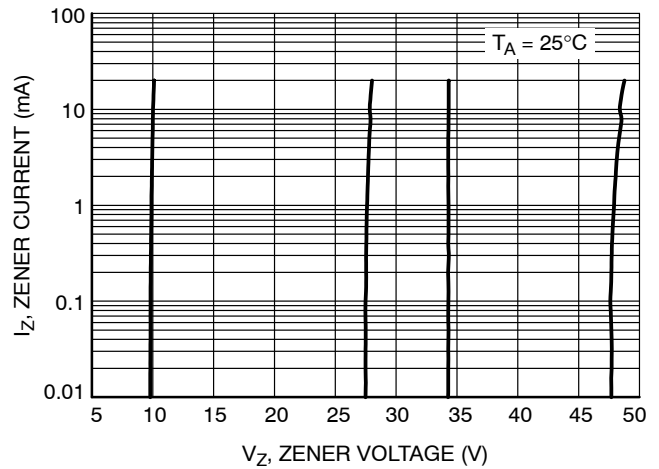
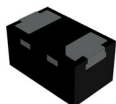


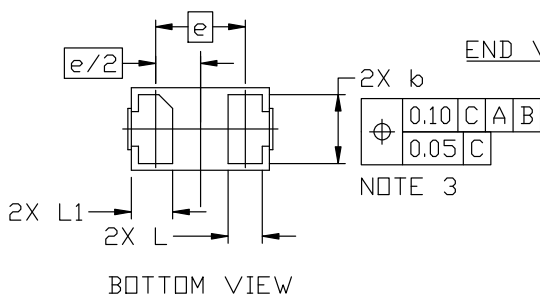
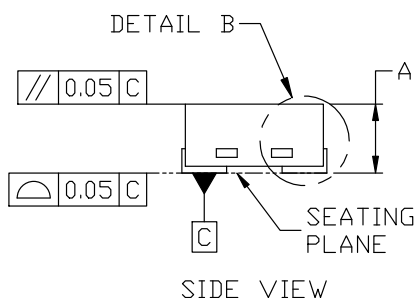
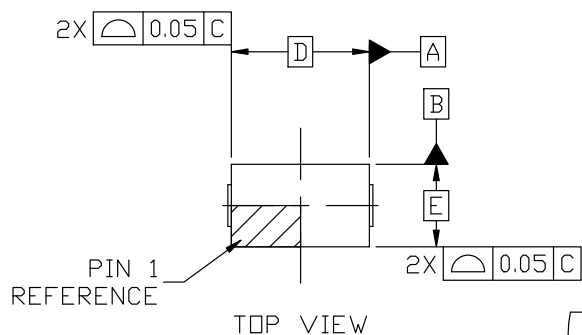
Figure 5. Zener Voltage vs. Zener Current

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



XDFNW2 1.00x0.60x0.50, 0.65P
CASE 521AE
ISSUE B

DATE 17 JAN 2024



GENERIC MARKING DIAGRAM*

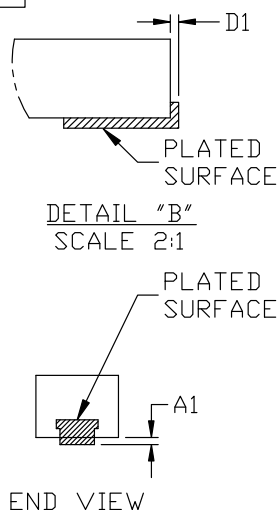


XX = Specific Device Code
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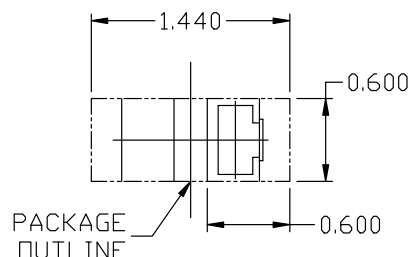
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. DIMENSION b APPLIES TO THE PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 FROM THE TERMINAL TIP.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.450	0.500	0.550
A1	---	---	0.050
b	0.450	0.500	0.550
D	1.000 BSC		
D1	---	---	0.050
E	0.600 BSC		
e	0.650 BSC		
L	0.220 REF		
L1	0.240	0.285	0.340



RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

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DESCRIPTION:	XDFNW2 1.00x0.60x0.50, 0.65P	PAGE 1 OF 1

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